



Material Declaration Data Sheet

Package Family	TO247PbF	
Date	2009/9/15	
Version	A	

Composition part	Material Description	Test Report	Weight (g)	Substance Name	CAS Number	Typical Substance weight(g)	%	PPM	% of Total Weight
Chip	Silicon		0.03620						
				Si	7440-21-3	0.03620	100.00	1000000	0.64%
Lead Frame	Copper	CE/2008/11298	3.73770						
				Cu	7440-50-8	3.73284	99.87	998700	66.49%
				Fe	7439-89-6	0.00374	0.10	1000	0.07%
				P	7723-14-0	0.00112	0.03	300	0.02%
Die Attach	J-Alloy	10120517/08(5)	0.01840						
				Tin	7440-31-5	0.01196	65.00	650000	0.21%
				Ag	7440-22-4	0.00460	25.00	250000	0.08%
				Sb	7440-36-0	0.00184	10.00	100000	0.03%
Wire Bond	Aluminum	LPCI/24740(B)/07	0.01020						
				Al	7429-90-5	0.01020	100.00	999950	0.18%
				Ni	7440-02-0	0.00000	0.01	50	0.00%
Encapsulation	Epoxy resin	CANEC0806161605	1.75684						
				Silicon dioxide	7631-86-9	1.55480	88.500	885000	27.70%
				Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylpheno	29690-82-2	0.14055	8.000	80000	2.50%
				Antimony trioxide	1309-64-4	0.05271	3.000	30000	0.94%
				Pigment Black 7	1333-86-4	0.00878	0.500	5000	0.16%
Lead Finish	Matte Tin	SH8001694	0.05450						
				Tin	7440-31-5	0.05412	99.30	993000	0.96%
				Cu	7440-50-8	0.00038	0.70	7000	0.01%
			5.61384						100.00%

EDIT		REVIEW		APPROVE	
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